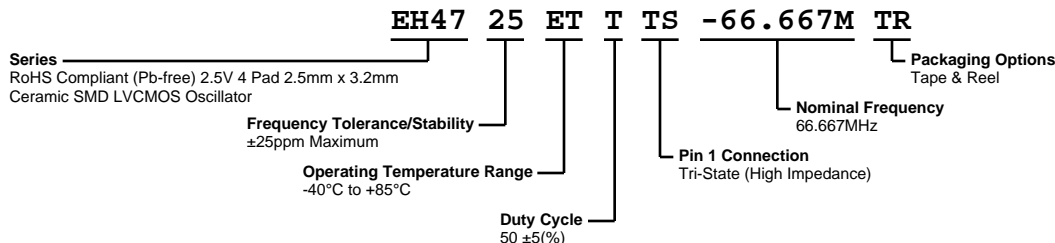


# EH4725ETTTS-66.667M TR



## ELECTRICAL SPECIFICATIONS

|                                       |   |
|---------------------------------------|---|
| Nominal Frequency                     | 66.667MHz   |
| Frequency Tolerance/Stability         | ±25ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°, 260°C Reflow, Shock, and Vibration) |
| Aging at 25°C                         | ±5ppm/Year Maximum  |
| Operating Temperature Range           | -40°C to +85°C  |
| Supply Voltage                        | 2.5Vdc ±5%  |
| Input Current                         | 7mA Maximum (No Load)   |
| Output Voltage Logic High (Voh)       | 90% of Vdd Minimum (IOH = -8mA)   |
| Output Voltage Logic Low (Vol)        | 10% of Vdd Maximum (IOL = +8mA)   |
| Rise/Fall Time                        | 4nSec Maximum (Measured at 20% to 80% of waveform)  |
| Duty Cycle                            | 50 ±5(%) (Measured at 50% of waveform)  |
| Load Drive Capability                 | 15pF Maximum  |
| Output Logic Type                     | CMOS  |
| Pin 1 Connection                      | Tri-State (High Impedance)  |
| Tri-State Input Voltage (Vih and Vil) | 90% of Vdd Minimum or No Connect to Enable Output, 10% of Vdd Maximum to Disable Output (High Impedance)  |
| Standby Current                       | 10µA Maximum (Pin 1 = Ground)   |
| Absolute Clock Jitter                 | ±100pSec Maximum  |
| Start Up Time                         | 10mSec Maximum  |
| Storage Temperature Range             | -55°C to +125°C   |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                              |   |
|------------------------------|---|
| ESD Susceptibility           | MIL-STD-883, Method 3015, Class 1, HBM: 1500Vdc |
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A           |
| Flammability                 | UL94-V0   |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C           |
| Mechanical Shock             | MIL-STD-883, Method 2002, Condition B           |
| Moisture Resistance          | MIL-STD-883, Method 1004                        |
| Moisture Sensitivity         | J-STD-020, MSL 1                                |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K            |
| Resistance to Solvents       | MIL-STD-202, Method 215                         |
| Solderability                | MIL-STD-883, Method 2003                        |
| Temperature Cycling          | MIL-STD-883, Method 1010, Condition B           |
| Vibration                    | MIL-STD-883, Method 2007, Condition A           |

# EH4725ETTS-66.667M TR

## MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION     |
|-----|----------------|
| 1   | Tri-State      |
| 2   | Case Ground    |
| 3   | Output         |
| 4   | Supply Voltage |

| LINE | MARKING   |
|------|---|
| 1    | EPO   |
| 2    | XXXXX<br>XXXXX=Ecliptek<br>Manufacturing Identifier |

## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

# EH4725ETTS-66.667M TR

## OUTPUT WAVEFORM & TIMING DIAGRAM



## Test Circuit for CMOS Output



Note 1: An external 0.1 $\mu$ F low frequency tantalum bypass capacitor in parallel with a 0.01 $\mu$ F high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

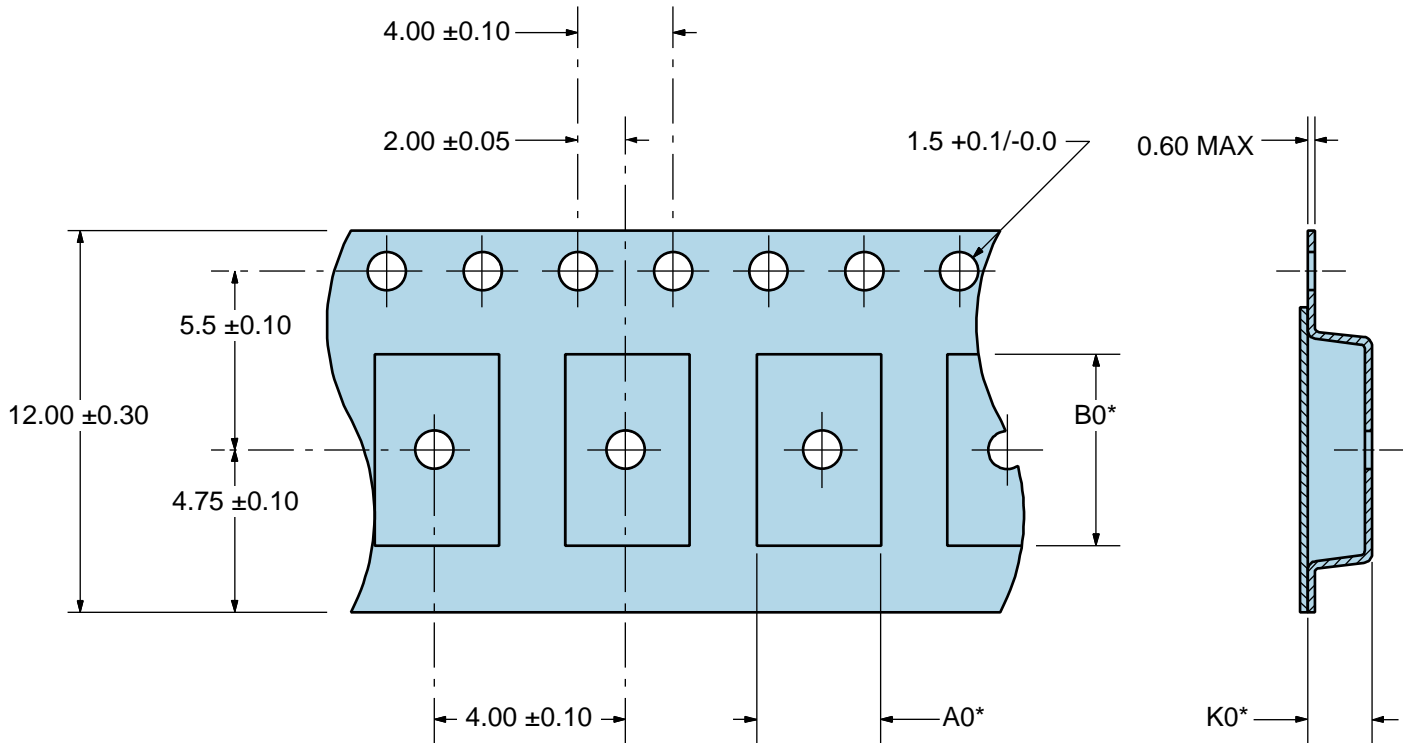
Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

# EH4725ETTS-66.667M TR

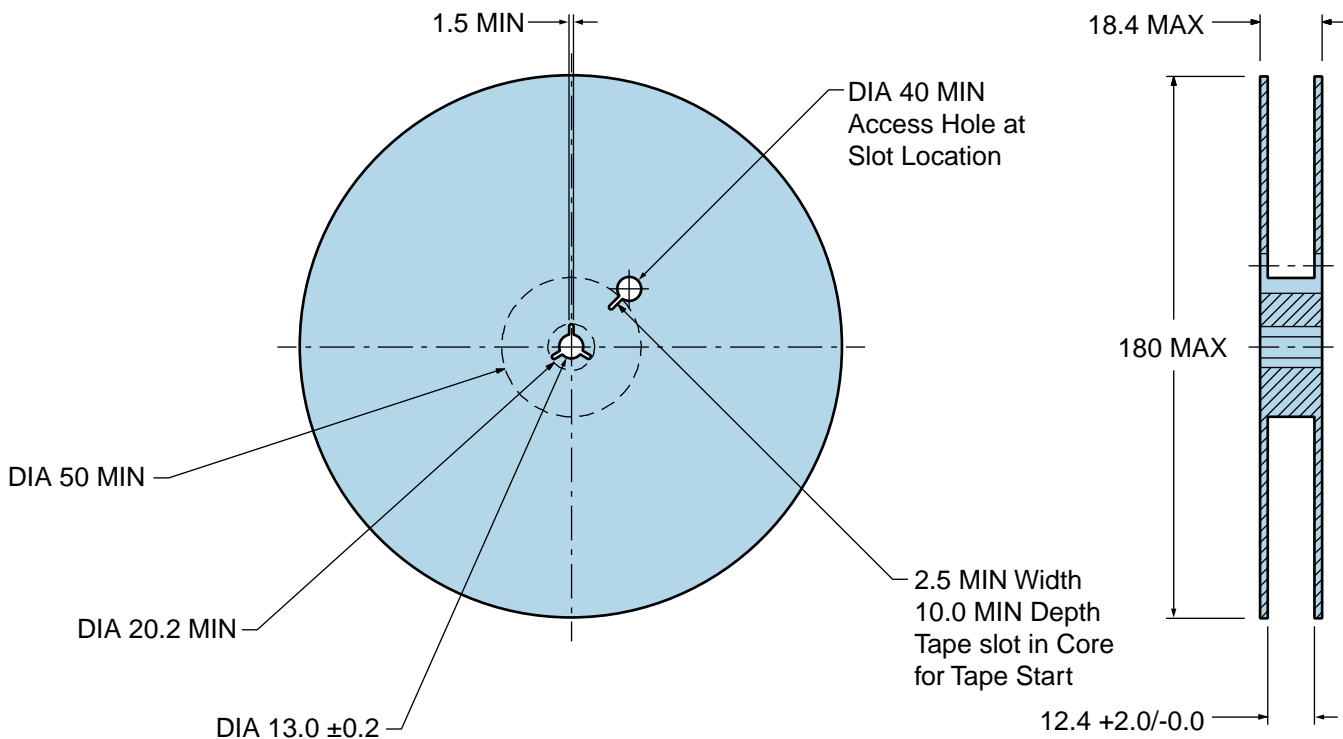


## Tape & Reel Dimensions

Quantity Per Reel: 1,000 units



\*Compliant to EIA 481A



## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

**$T_s$  MAX to  $T_L$  (Ramp-up Rate)** 3°C/second Maximum

#### Preheat

- Temperature Minimum ( $T_s$  MIN) 150°C
- Temperature Typical ( $T_s$  TYP) 175°C
- Temperature Maximum ( $T_s$  MAX) 200°C
- Time ( $t_s$  MIN) 60 - 180 Seconds

**Ramp-up Rate ( $T_L$  to  $T_p$ )** 3°C/second Maximum

#### Time Maintained Above:

- Temperature ( $T_L$ ) 217°C
- Time ( $t_L$ ) 60 - 150 Seconds

**Peak Temperature ( $T_p$ )** 260°C Maximum for 10 Seconds Maximum

**Target Peak Temperature ( $T_p$  Target)** 250°C +0/-5°C

**Time within 5°C of actual peak ( $t_p$ )** 20 - 40 seconds

**Ramp-down Rate** 6°C/second Maximum

**Time 25°C to Peak Temperature (t)** 8 minutes Maximum

**Moisture Sensitivity Level** Level 1

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

|  |  |
|--|--|
| <b>T<sub>s</sub> MAX to T<sub>L</sub> (Ramp-up Rate)</b> | 5°C/second Maximum                                     |
| <b>Preheat</b>   |  |
| - Temperature Minimum (T <sub>s</sub> MIN)               | N/A  |
| - Temperature Typical (T <sub>s</sub> TYP)               | 150°C  |
| - Temperature Maximum (T <sub>s</sub> MAX)               | N/A  |
| - Time (t <sub>s</sub> MIN)                              | 60 - 120 Seconds                                       |
| <b>Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)</b>     | 5°C/second Maximum                                     |
| <b>Time Maintained Above:</b>                            |  |
| - Temperature (T <sub>L</sub> )                          | 150°C  |
| - Time (t <sub>L</sub> )                                 | 200 Seconds Maximum                                    |
| <b>Peak Temperature (T<sub>P</sub>)</b>                  | 240°C Maximum  |
| <b>Target Peak Temperature (T<sub>P</sub> Target)</b>    | 240°C Maximum 1 Time / 230°C Maximum 2 Times           |
| <b>Time within 5°C of actual peak (t<sub>p</sub>)</b>    | 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time |
| <b>Ramp-down Rate</b>                                    | 5°C/second Maximum                                     |
| <b>Time 25°C to Peak Temperature (t)</b>                 | N/A  |
| <b>Moisture Sensitivity Level</b>                        | Level 1  |

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.